

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF464A-F11 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2012-2-11 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

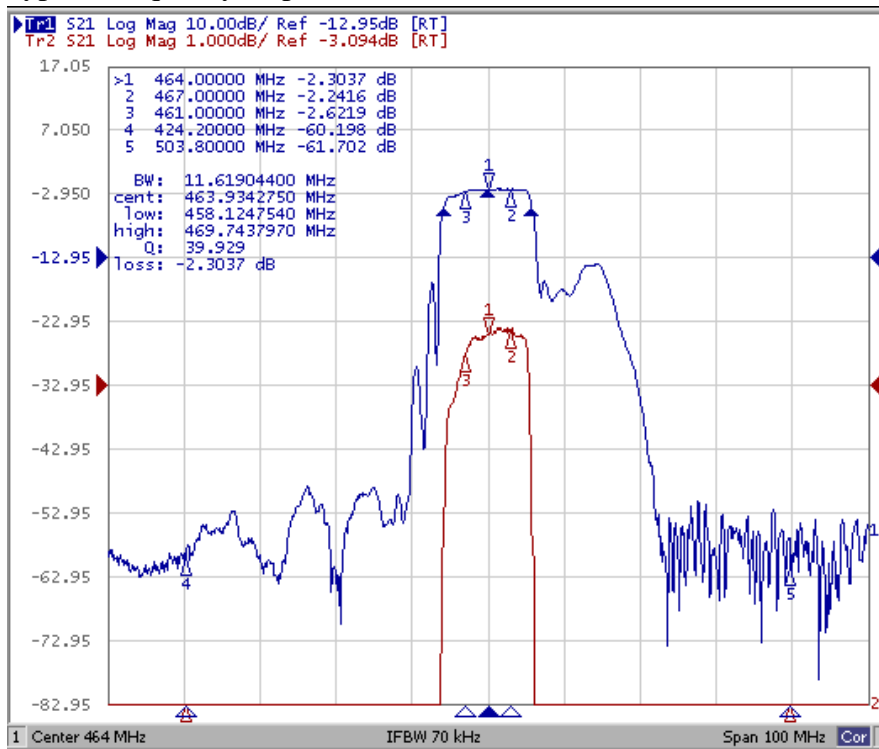
This specification shall cover the characteristics of SAW filter With F464AF11 used for the page system.

## 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

### Electronic Characteristics

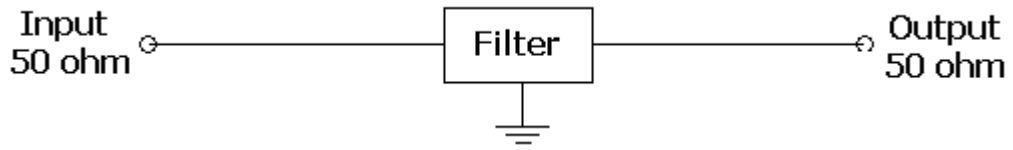
#### 2-1. Typical frequency response



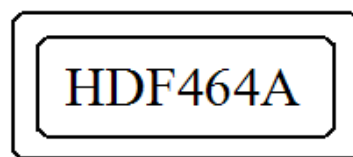
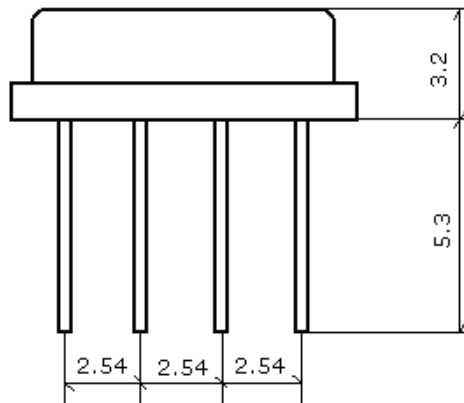
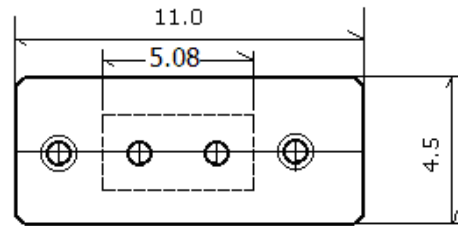
#### 2-2. Electrical characteristics

Part number	F464A	Unit
Nominal center frequency (Fo)	464	MHz
Insertion Loss		
1.fo-45.8~fo-39.8 MHz	50min.	dB
2.fo ± 3.0 MHz	4.0max.	
3.fo +39.8~ fo +45.8MHz	45min.	
Ripple (with Fo ± 3.0MHz)	2.0max	dB
Input/Output Impedance(Nominal)	50//0	Ω /pF

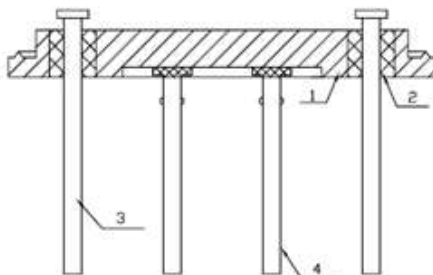
**3. TEST CIRCUIT**



**4. DIMENSION**



**4.2 Materials**



序号	名称	材质	数量
1	基座材料	SPCC	1
2	绝缘体材料	玻璃粉	2
3	引出脚材料	4J29	4
4	引出脚搪锡	Tin 与引脚距离<0.8mm	4
	基座电镀	Ni >2.5um	1

## **5. ENVIRONMENTAL CHARACTERISTICS**

### **5-1 Temperature cycling**

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

### **5-2 Resistance to solder heat**

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

### **5-3 Solderability**

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

### **5-4 Mechanical shock**

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

### **5-5 Vibration**

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

## **6. REMARK**

### **6.1 Static voltage**

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### **6.2 Ultrasonic cleaning**

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### **6.3 Soldering**

Only leads of component may be soldered. Please avoid soldering another part of component.